

FOR: BE SEMICONDUCTOR INDUSTRIES N.V.
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PRESS RELEASE

BE Semiconductor Industries Announces New RFID Orders and Swiss Development Facility

Duiven, the Netherlands, February 22, 2007, BE Semiconductor Industries N.V. ("the Company" or "Besi") (Euronext: BESI), a leading manufacturer of assembly equipment for the semiconductor industry, today announced that its Datacon subsidiary received three orders aggregating approximately US\$ 3.3 million for its 8800 FC ("Flip Chip") Smart Line die bonding system. The orders were placed by a Chinese government organization and by a Korean and American semiconductor manufacturer, respectively, for Radio Frequency Identification Device ("RFID") applications. The orders are anticipated to be delivered in the second quarter of 2007.

Datacon's 8800 FC Smart Line system is a fully automated, high-performance production line providing customers a complete RFID chip assembly solution based on a highly cost-effective method of direct chip attach to RFID antennae. In particular, the Chinese order was obtained via a competitive tender to help produce the enormous quantity of RFID tags required for the upcoming Beijing Olympic Games in 2008. In general, RFID technology has been defined as one of the key items in the next five year development program by the Chinese government.

In addition, Besi announced the establishment by Datacon of a new subsidiary based in Baar, Switzerland dedicated to the research and development of micromechanical systems and process technologies to help support and advance the progress of its die bonding operations. The Baar location was selected due to its proximity to the Swiss Federal Institute of Technology in Zurich and a number of Datacon's suppliers and its high concentration of personnel nearby with expertise in process and chip technologies. The Company intends to initially lease an approximate 3,300 square foot facility and to hire between 5-10 research personnel within its first full year of operation.

About BE Semiconductor Industries N.V.

BE Semiconductor Industries N.V. designs, develops, manufactures, markets and services die sorting, flip chip and multi-chip die bonding, packaging and plating equipment for the semiconductor industry's assembly operations. Its customers consist primarily of leading U.S., European, Asian, Korean and Japanese semiconductor manufacturers and subcontractors which utilize its products for both array connect and conventional leadframe manufacturing processes. For more information about Besi, please visit our website at www.besi.com.

Caution Concerning Forward Looking Statements

This press release contains forward-looking statements, which are found in various places throughout the press release, including statements relating to expectations of orders, net sales, product shipments, backlog, expenses, timing of purchases of assembly equipment by customers, gross margins, operating results and capital expenditures. The words “anticipate”, “estimate”, “expect”, “can”, “intend”, “believes”, “may”, “plan”, “predict”, “project”, “forecast”, “will”, “would”, and similar expressions are intended to identify forward looking statements, although not all forward looking statements contain these identifying words. While these forward looking statements represent our judgments and future expectations concerning the development of our business, a number of risks, uncertainties and other important factors could cause actual developments and results to differ materially from our expectations. These factors include, but are not limited to, those listed or discussed in Besi’s Annual Report for the year ended December 31, 2005, as well as the risk that anticipated orders may not materialize or that orders received may be postponed or canceled, generally without charges; the volatility in the demand for semiconductors and our products and services; acts of terrorism and violence; overall global economic conditions; risks, such as changes in trade regulations, currency fluctuations, political instability and war, associated with substantial foreign customers, suppliers and foreign manufacturing operations; potential instability in foreign capital markets; the risk of failure to successfully manage our expanding and more diverse operations; and other key factors that could adversely affect our businesses and financial performance contained in our filings and reports, including our statutory consolidated statements. We are under no obligation to (and expressly disclaim any such obligation to) update or alter our forward-looking statements whether as a result of new information, future events or otherwise.

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